

FIG. 1

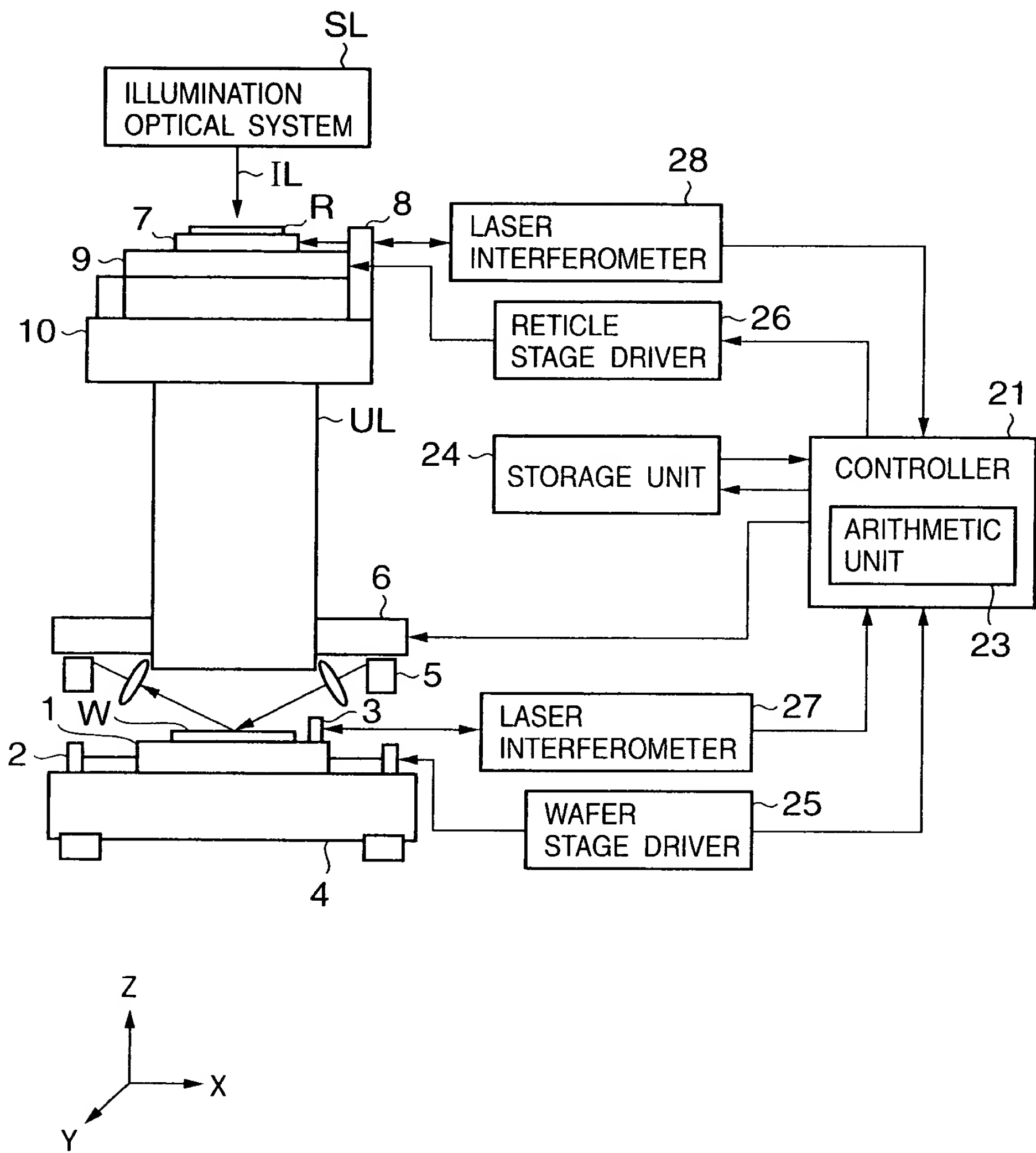


FIG. 2

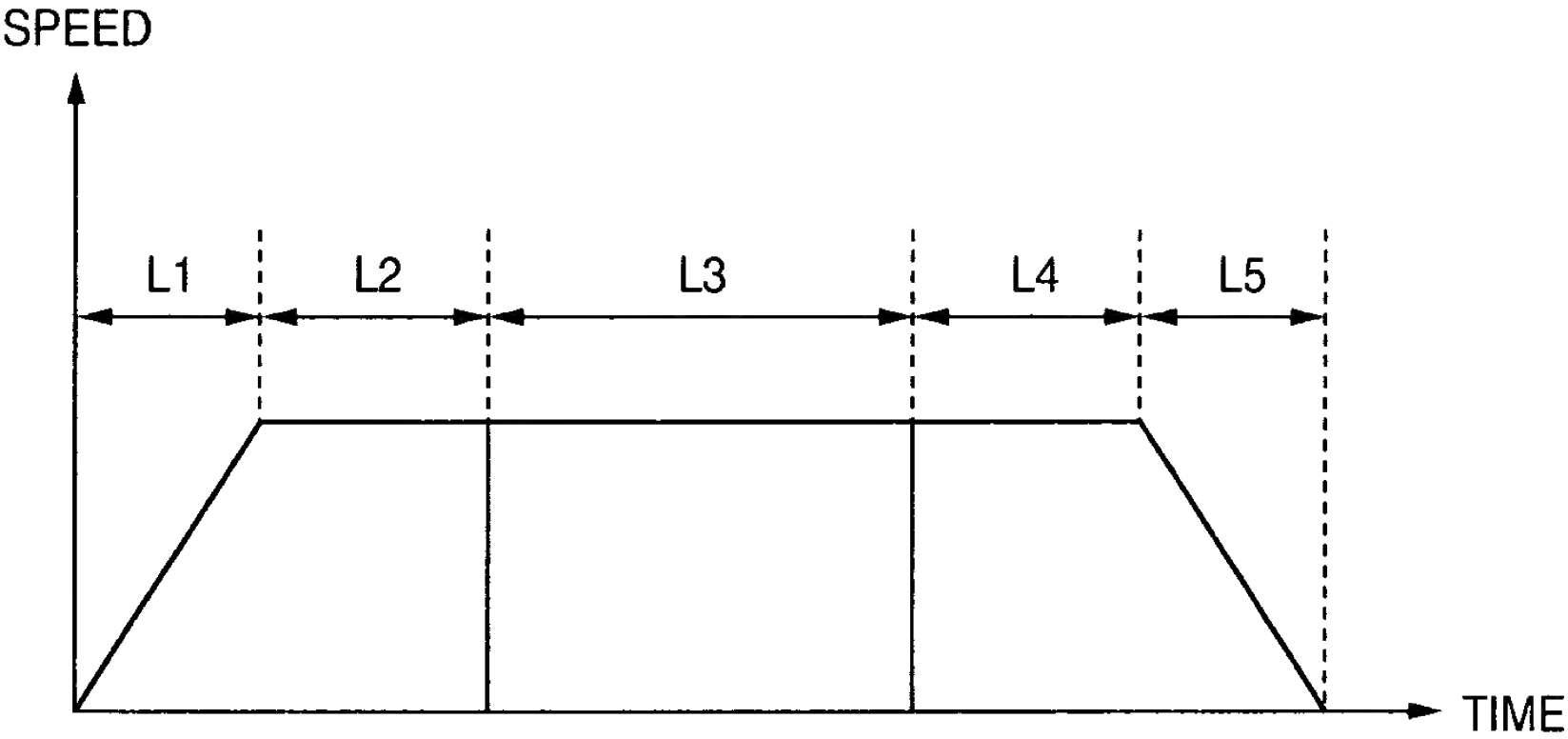
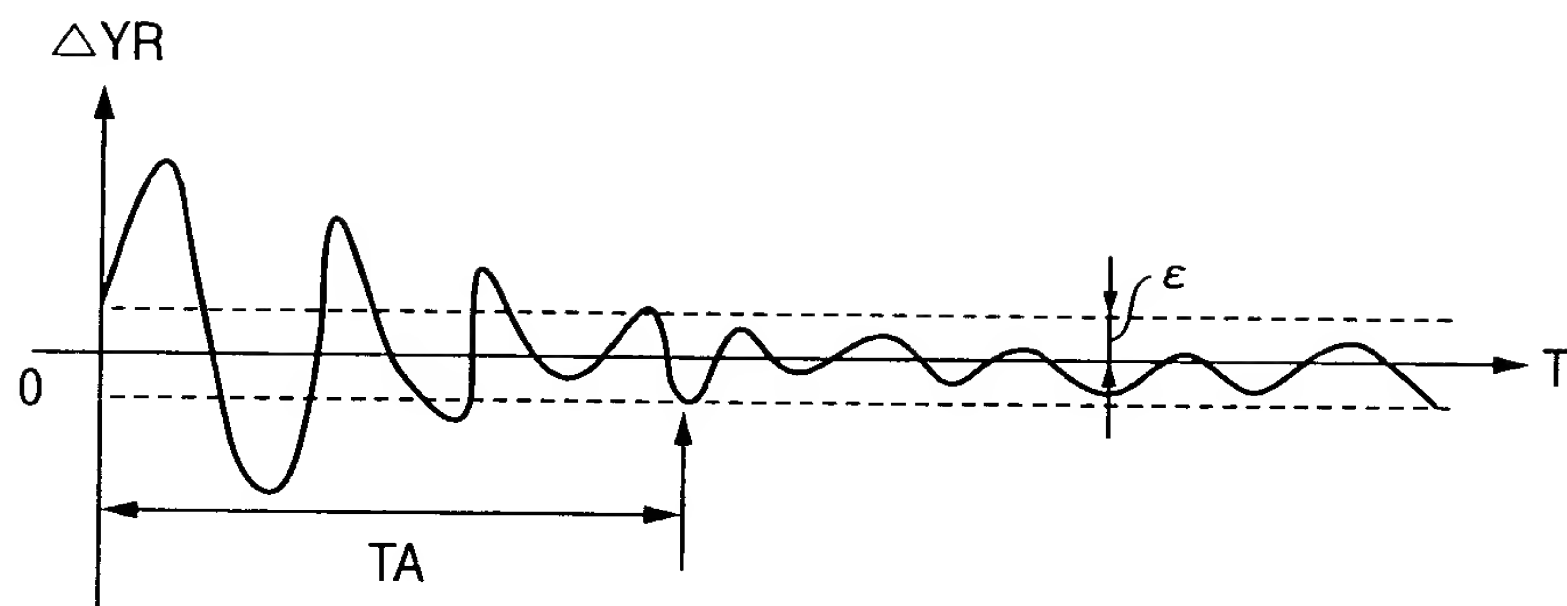
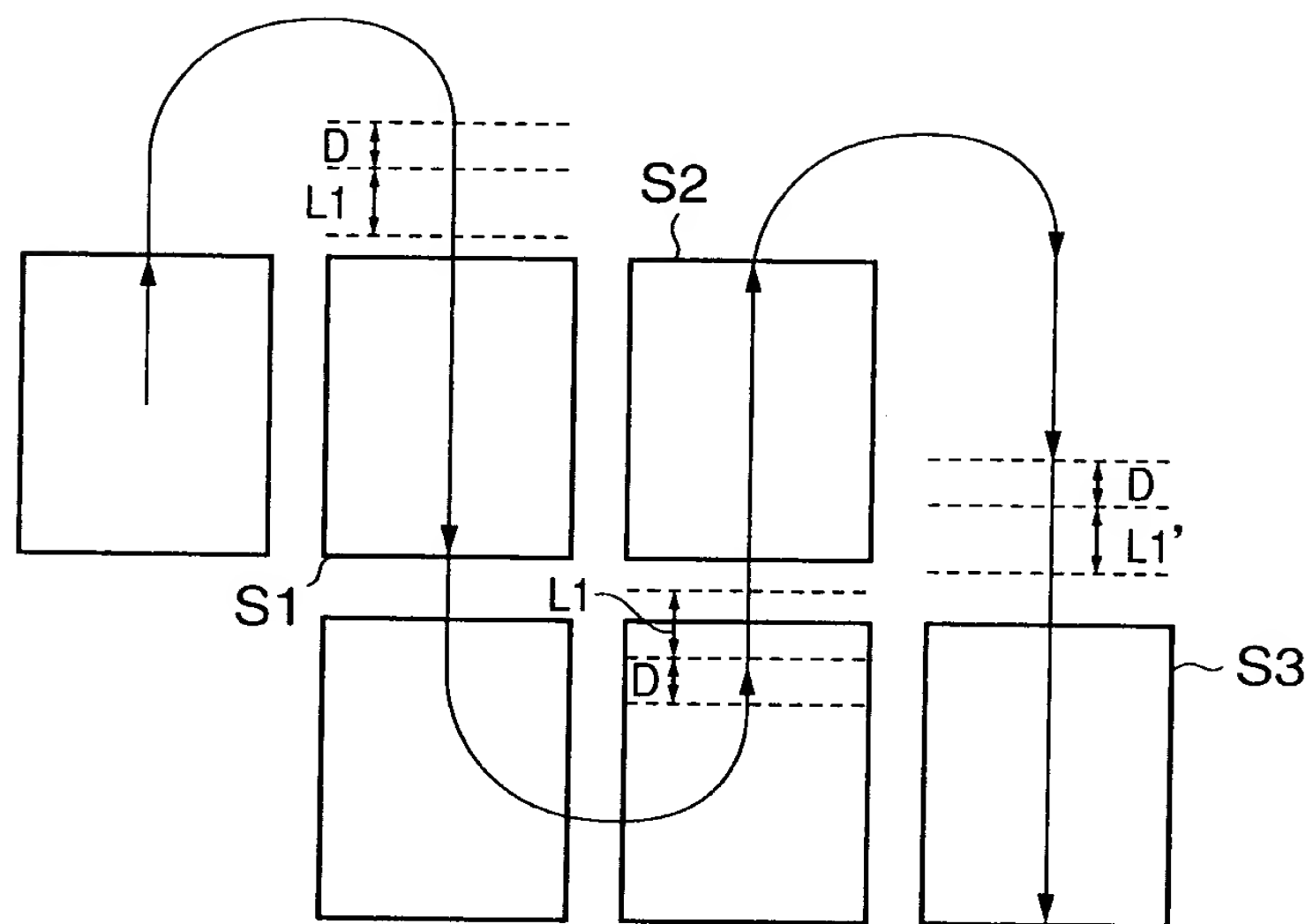


FIG. 2

**FIG. 3**

**FIG. 4**



$$L1 < L1'$$

FIG. 4

**FIG. 5**

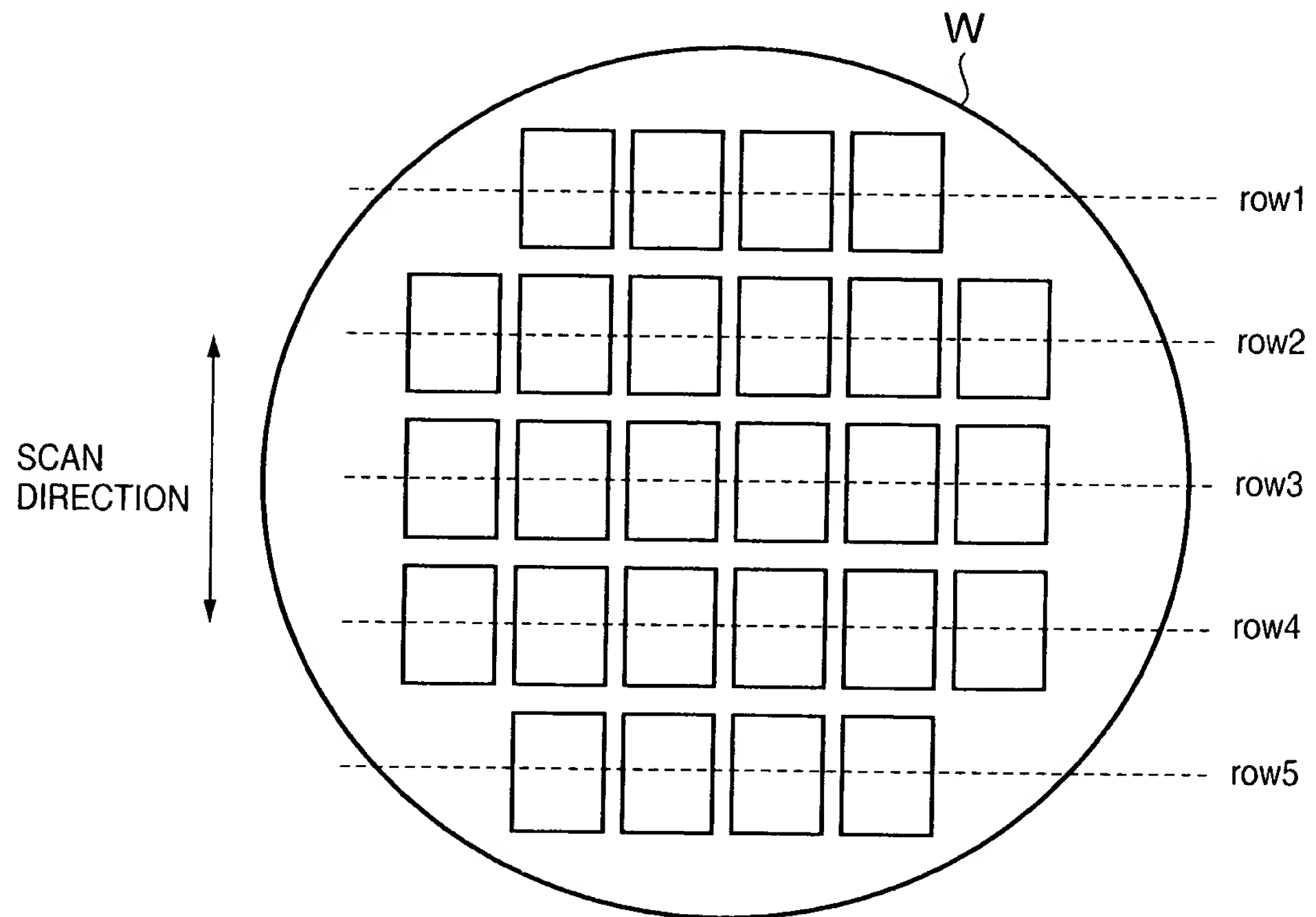


FIG. 5

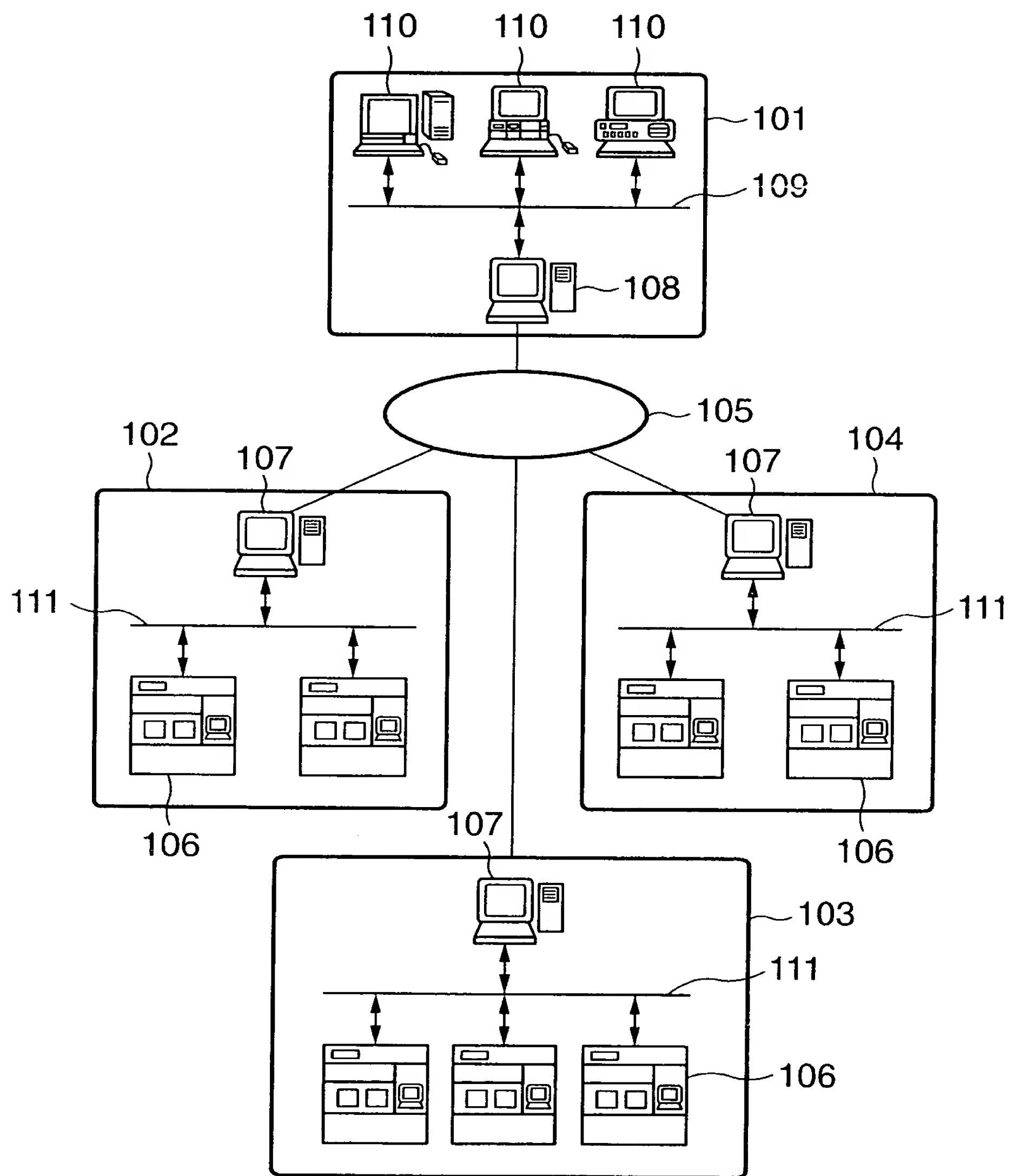
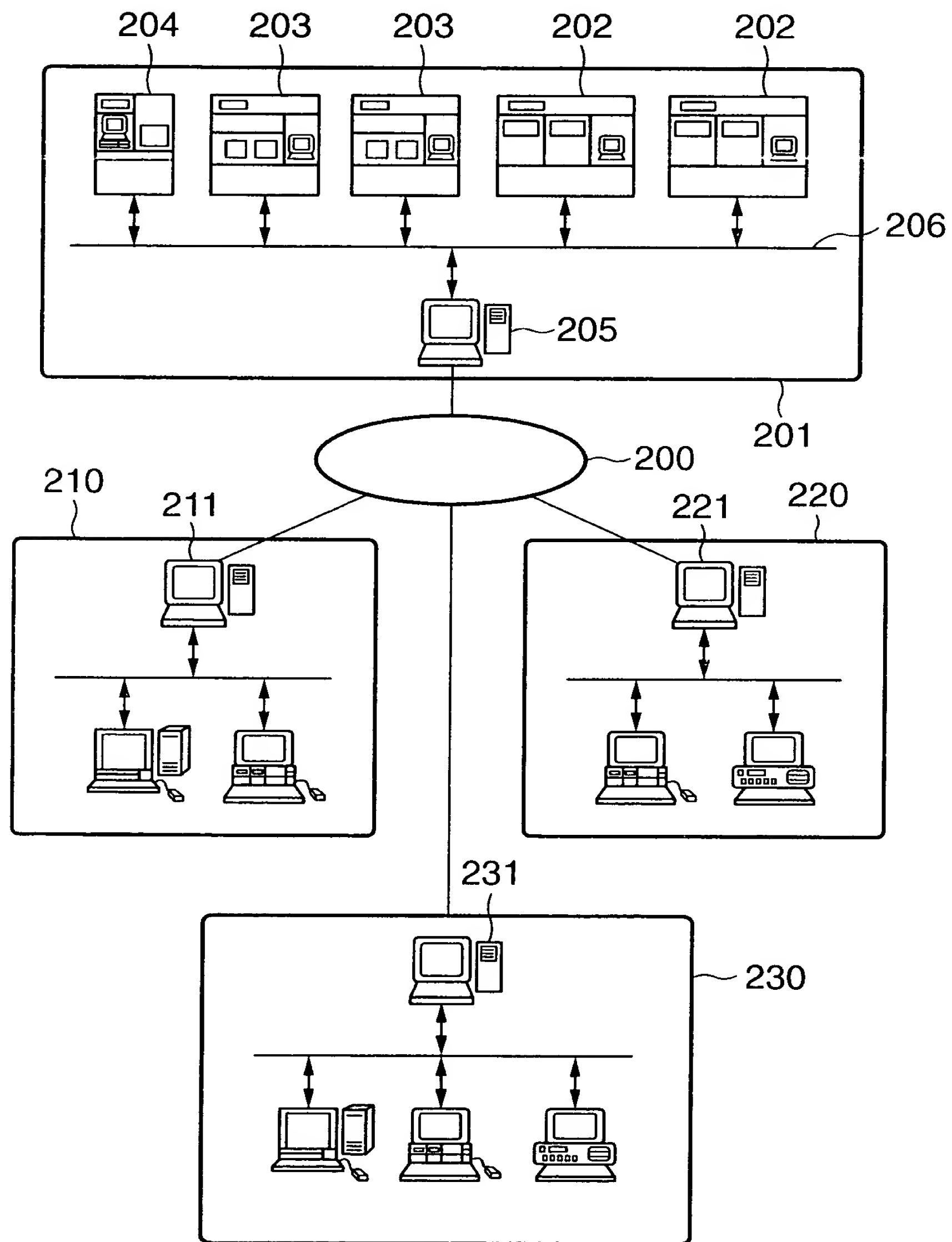
**FIG. 6**

FIG. 7



**FIG. 8**

URL

TROUBLE DB INPUT WINDOW

OCCURRENCE DATE  ~ 404

TYPE OF APPARATUS  ~ 401

SUBJECT  ~ 403

SERIAL NUMBER S/N  ~ 402

DEGREE OF URGENCY  ~ 405

SYMPTOM  ~ 406

REMEDY  ~ 407

PROGRESS  ~ 408

410

411

412



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graph TD; S1[DESIGN CIRCUIT] --> S2[FORM MASK]; S2 --> S4[WAFER PROCESS<br/>(PRE-PROCESS)]; S3[WAFER MANUFACTURE] --> S4; S4 --> S5[ASSEMBLY<br/>(POST-PROCESS)]; S5 --> S6[INSPECTION]; S6 --> S7[SHIPPING];
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The flowchart illustrates the semiconductor manufacturing process, consisting of seven sequential steps:

- DESIGN CIRCUIT** (STEP1)
- FORM MASK** (STEP2)
- WAFER MANUFACTURE** (STEP3)
- WAFER PROCESS (PRE-PROCESS)** (STEP4)
- ASSEMBLY (POST-PROCESS)** (STEP5)
- INSPECTION** (STEP6)
- SHIPPING** (STEP7)

The process flow is as follows:

- Step 1 (DESIGN CIRCUIT) leads to Step 2 (FORM MASK).
- Step 2 (FORM MASK) leads to Step 4 (WAFER PROCESS (PRE-PROCESS)).
- Step 3 (WAFER MANUFACTURE) also leads to Step 4 (WAFER PROCESS (PRE-PROCESS)).
- Step 4 (WAFER PROCESS (PRE-PROCESS)) leads to Step 5 (ASSEMBLY (POST-PROCESS)).
- Step 5 (ASSEMBLY (POST-PROCESS)) leads to Step 6 (INSPECTION).
- Step 6 (INSPECTION) leads to Step 7 (SHIPPING).

# SEMICONDUCTOR DEVICE MANUFACTURING FLOW

FIG. 10

